

ABSTRACT OF THE DISCLOSURE

The object of the present invention is to provide a flat-panel-display substrate which is high in heat resistance, of which the coefficient of thermal expansion is approximated to that of a thick film dielectric layer, which is low at high temperatures in reactivity with the lead-doped thick film dielectric layer, and which can be made to have a large area. The substrate of the present invention is obtained by sintering a body comprising glass powder and a filler made of metal and/or semi-metal oxide, and is constituted by the sintered body and whose average coefficient of linear thermal expansion is from 7 to 9.5 ppm/°C in the temperature range of 25 to 700 °C. The glass powder includes alkaline-earth oxide, 15 to 50% by weight of silicon oxide, and no greater than 2% by weight of boron oxide. Furthermore, the filler is at a concentration of 10 to 30% by volume of the total amount of the glass powder and the filler in the mould.